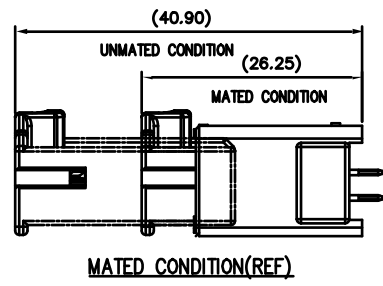
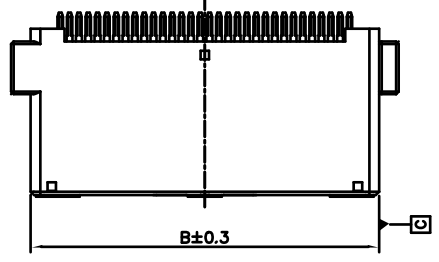
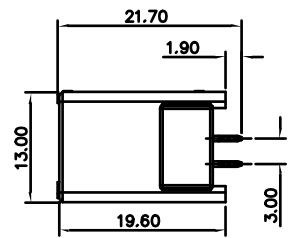
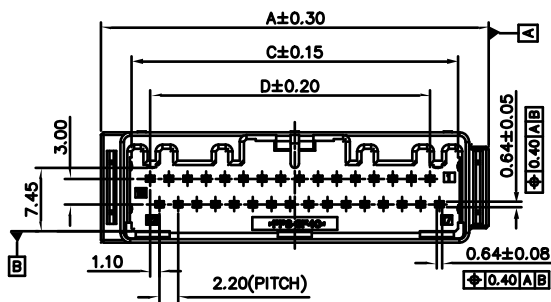


REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
1			INITIAL RELEASE	2023.03.14	Yy_D

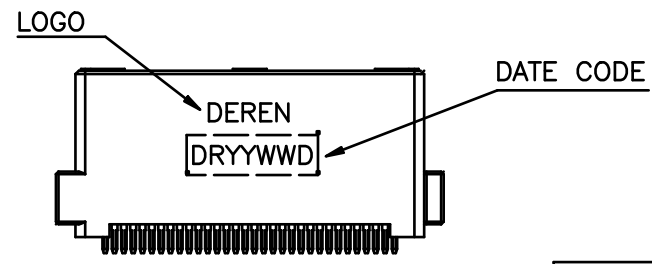


NOTES:  
 PRODUCT MEETS CONTROLLED SUBSTANCES SPEC. ROHS 2.0  
 1. MATERIAL:  
 1.1 HOUSING: PPS, UL94V-0; COLOR: BLACK.  
 1.2 CONTACT: BRASS.  
 2. FINISH:  
 2.1 CONTACT: TIN ON CONTACT AREA.  
 50u"~100u"MIN. TIN PLATING ON SOLDER TAIL AREA.  
 100u"~180u". NICKEL UNDERPLATING OVERALL.  
 3. ELECTRICAL SPECIFICATION:  
 3.1 VOLTAGE RATING: 50V MAX. AC/DC.  
 3.2 CURRENT RATING: 3A MAX. AC/DC.  
 3.3 WITHSTANDING VOLTAGE: 1000V AC/MINUTE.  
 3.4 TEMPERATURE RANGE: -40°C~+125°C  
 3.5 INSULATION RESISTANCE: 1000MΩ.  
 3.6 CONTACT RESISTANCE: <5MΩ MAX.AFTER ENVIRONMENT TESTING:<10MΩ




570CBG-032R\*\*\*T\*\*

CUSTOMER CODE  
 T:TUBE  
 R:REEL  
 PIN:  
 12:12PIN  
 .....  
 40:40PIN  
 PLATING:  
 1:MATTE-SN  
 2:BRIGHT SN  
 SPECIAL NO.  
 1:WITH LOGO  
 2:WITHOUT LOGO  
 R:RoHS  
 H:HALOGEN-FREE  
 WAFER



Poles	Dimensions (mm)			
	A	B	C	D
2*06	23.70	19.10	16.50	11.00
2*08	28.10	23.50	20.90	15.40
2*10	32.50	27.90	25.30	19.80
2*12	36.90	32.30	29.70	24.20
2*14	41.30	36.70	34.10	28.60
2*16	45.70	41.10	38.50	33.00
2*18	50.10	45.50	43.00	37.40
2*20	54.50	49.90	47.40	41.80

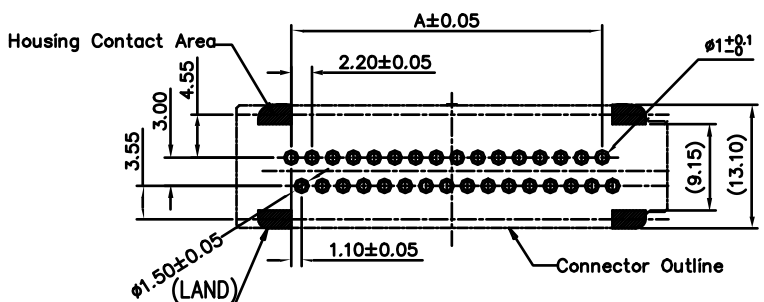
DIM	TOL	DIM	TOL
x	±0.35	x	±2'
.x	±0.30		
.xx	±0.25		

	<b>DEREN</b> SHENZHEN DEREN ELECTRONIC CO., LTD			
	CUSTOMER DRAWING	DATE	TITLE: WAFER 2.20PH 19.8H VERTICAL DIP GOWN	
	DESIGN: Yy_D	2023.03.14	P/N:SEE TABLE	
	CHECK:		SHEET: 1/3	UNIT: mm
REV. 1	APPROVAL:			

1 2 3 4 5 6 7 8

A

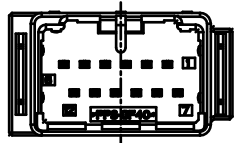
A



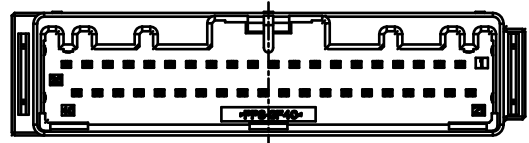
APPLICABLE P.C.B LAYOUT(REF.)  
P.C.B THICKNESS t=1.6mm

B

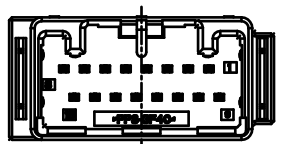
B



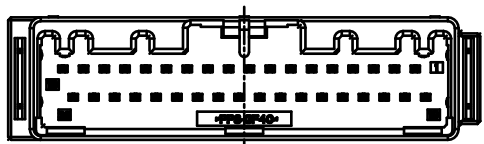
2\*06PIN



2\*20PIN



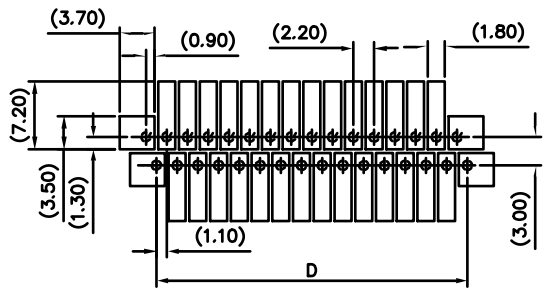
2\*08PIN



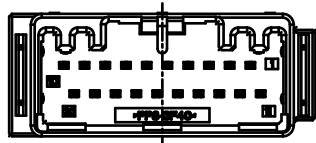
2\*18PIN

C

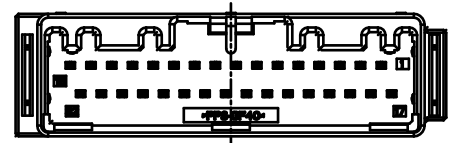
C



METAL MASK DIMENSIONS(REF)  
MASK THICKNESS T=0.15mm



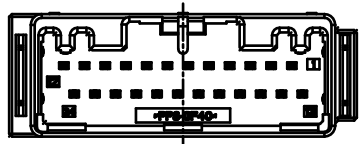
2\*10PIN



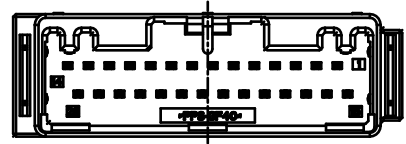
2\*16PIN

D

D



2\*12PIN



2\*14PIN

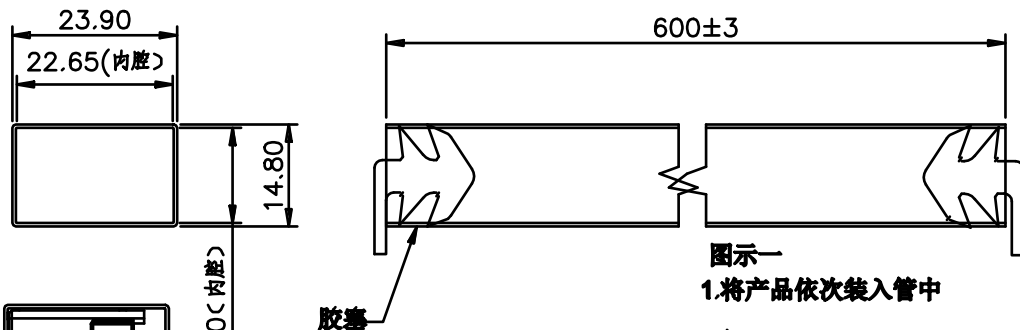
E

E

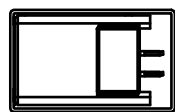
1 2 3 4 5 6 7 8

DIM	TOL	DIM	TOL
x	±0.35	x	±2°
.x	±0.30		
.xx	±0.25		

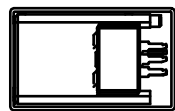
	<b>DEREN</b>		
	SHENZHEN DEREN ELECTRONIC CO., LTD		
	CUSTOMER DRAWING	DATE	TITLE: WAFER 2.20PH 19.0H VERTICAL DIP CONN
	DESIGN: yy_D	2023.03.14	P/N:SEE TABLE
DRAW NO. ***	CHECK:	SHEET: 2/3	
REV. 1	APPROVAL:	SCALE: 1:1	



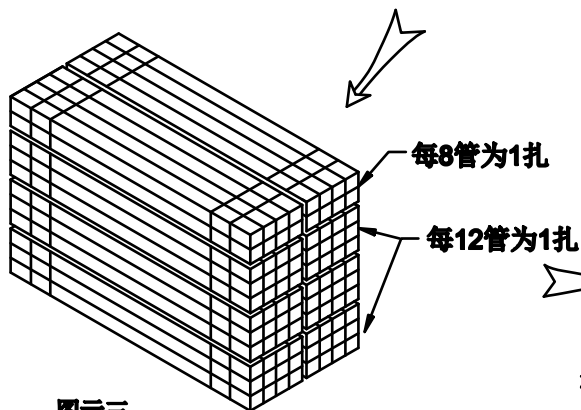
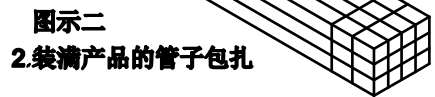
图示一  
1.将产品依次装入管中



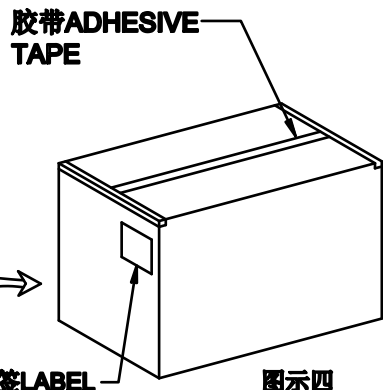
匹配图不带鱼叉



匹配图带鱼叉



图示三  
3.将每扎管子包扎





图示四  
4.装箱, 封胶

说明:

- 1.将产品依图示方向放入真空管内, 方向须一致, 每个真空管放的产品数量依Pin数不同而不同, 具体详见包装明细表, 真空管两头用胶塞塞住, 如图示一。
- 2.将装好产品的真空管平放在桌面上以4PCS为一排然后再叠放3列或2列为1把如图二或图三, 整理好后用PE膜将1把真空管两头PE膜缠绕包好, 并在左边PE膜处贴1PCS产品标签, 如图示二。
- 3.将上步完成的产品以每把进行包扎, 包装成一整扎, 以图示三
- 4.将包扎好产品放入纸箱内, 并将纸箱用胶带封好, 在其侧面右上角贴上出货标签。
- 5.纸箱规格: 600\*200\*180mm 真空管规格: 600\*14.4\*14.6mm
- 6.纸箱厚度: 6~7mm

PIN数	每支真空产品数量PCS/管	每箱真空管数量 PCS管/箱	每箱包装数量 PCS/箱
2*06	24	88	2112
2*08	20	88	1760
2*10	17	88	1496
2*12	15	88	1320
2*14	13	88	1144
2*16	12	88	1056
2*18	11	88	968
2*20	10	88	880

DIM	TOL	DIM	TOL
x	/	x	/
.x	/		/
.xx	/		/

	<b>DEREN</b> SHENZHEN DEREN ELECTRONIC CO., LTD		
	CUSTOMER DRAWING	DATE	TITLE: WAFER 2.20PH 19.8H VERTICAL DIP CONN
DESIGN: Yy_D	2023.03.14	P/N: SEE TABLE	
CHECK:		SHEET: 3/3	
APPROVAL:		SCALE: N/A	UNIT: mm
REV: 1			